

WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD  
THEREOF

Inventor: Joo Ho LEE  
Docket No. 2336-248

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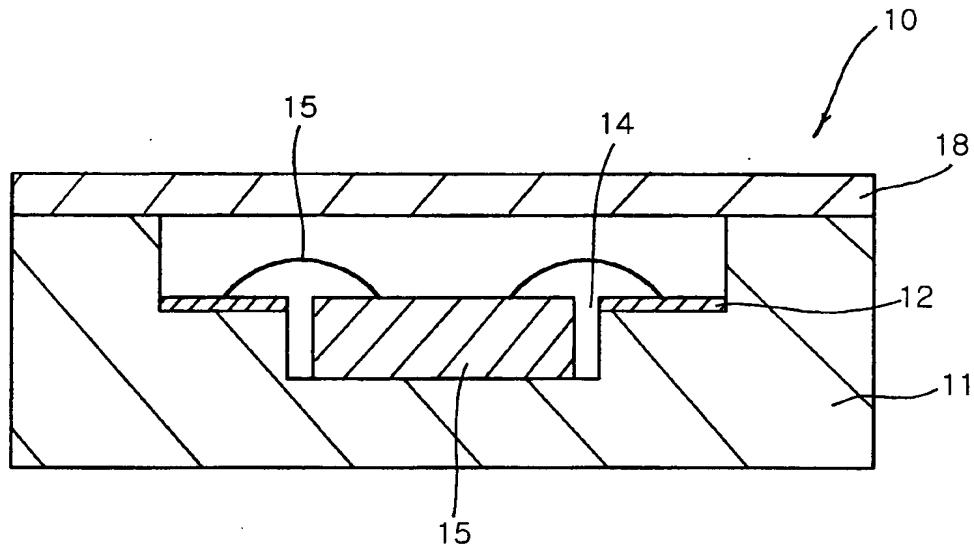


FIG. 1  
PRIOR ART

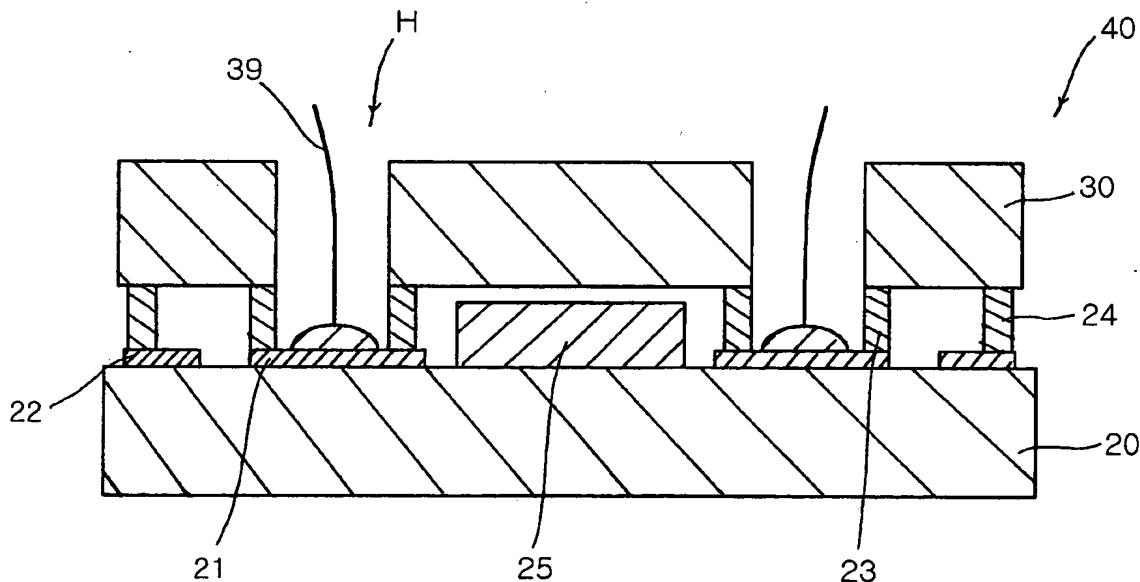


FIG. 2  
PRIOR ART

WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD

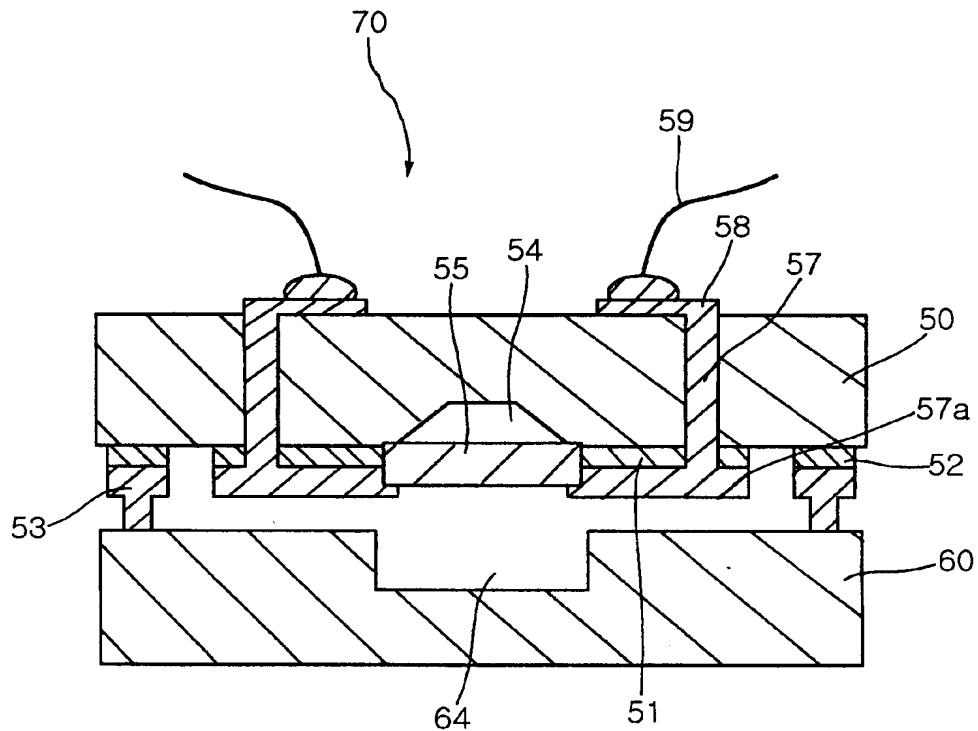
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(a)



(b)

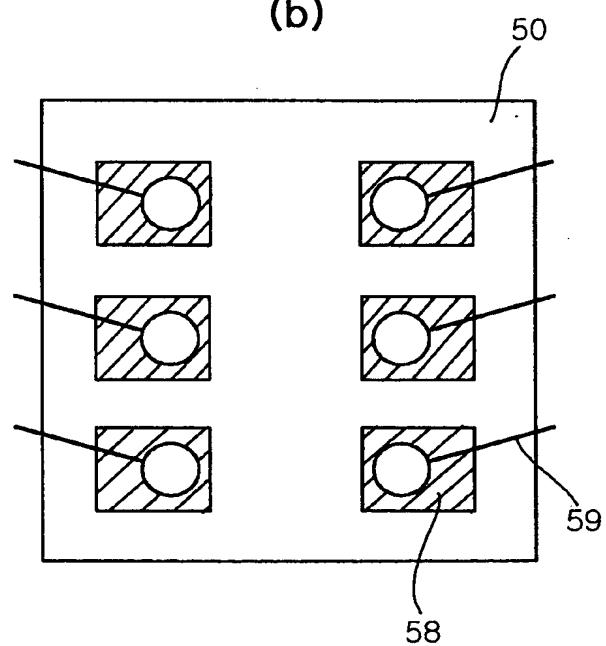


FIG. 3

WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD

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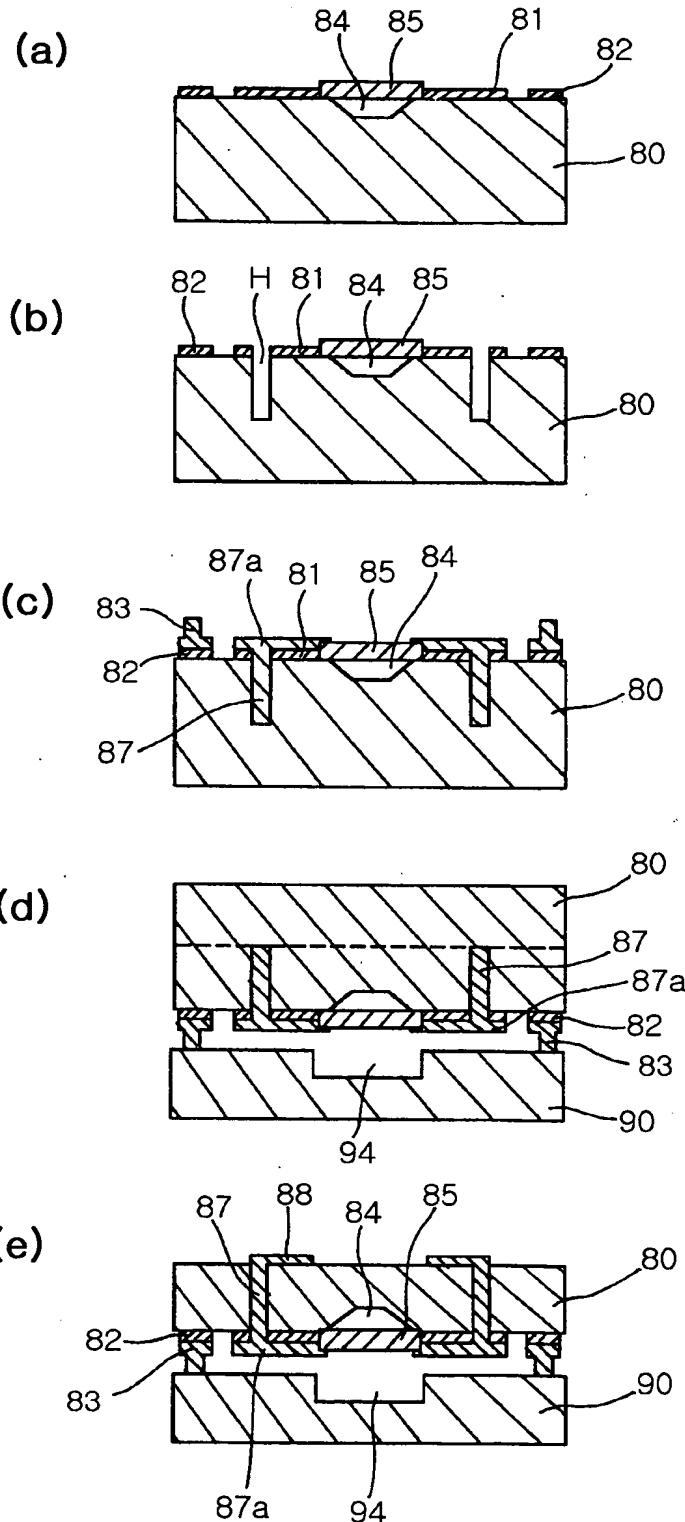


FIG. 4

WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD

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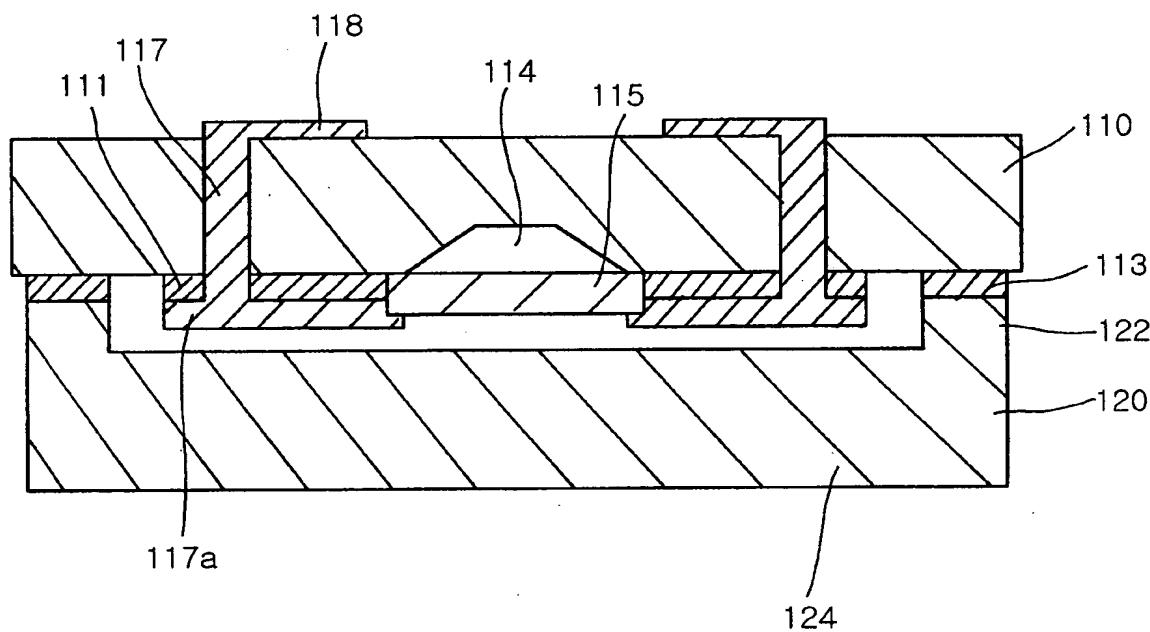


FIG. 5

WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD

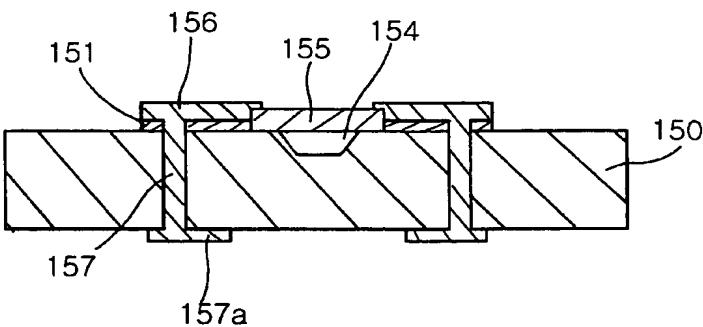
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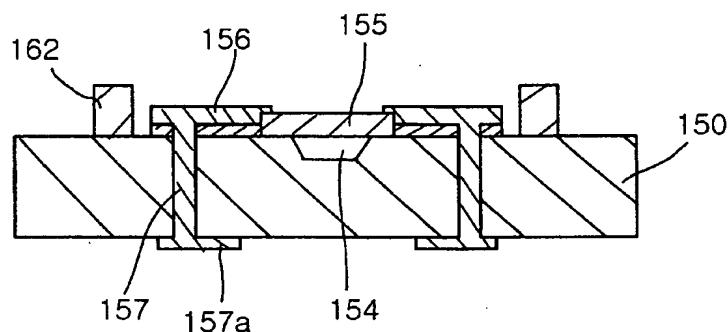
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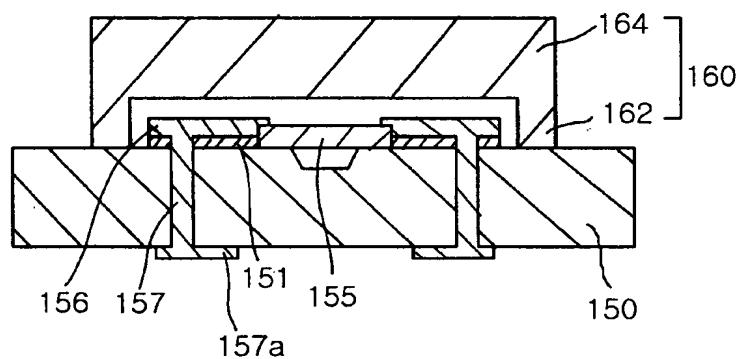
(a)



(b)



(c)



(d)

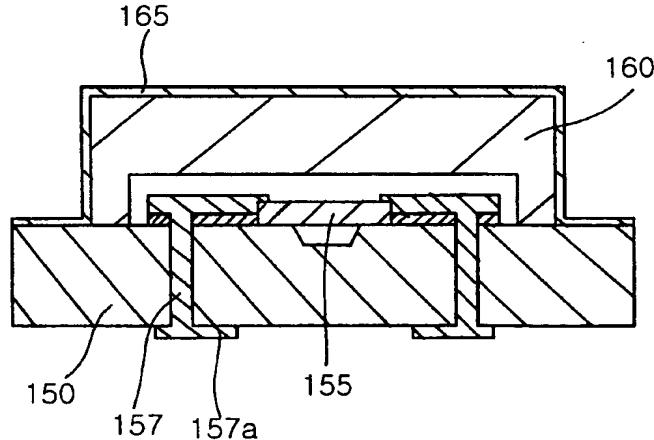


FIG. 6